



Attorney's Docket No.: Intel 10559-857001 / P17305

IFW

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Sarah E. Kim et al. Art Unit : 2814
Serial No.: 10/659,044 Examiner : Thao X. Le
Filed : September 9, 2003
Assignee : Intel Corporation
Title : THICK METAL LAYER INTEGRATED PROCESS FLOW TO IMPROVE
POWER DELIVERY AND MECHANICAL BUFFERING

Mail Stop Amendment

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO RESTRICTION REQUIREMENT

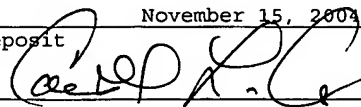
Responsive to the action mailed October 15, 2004, applicant elects the invention of Group I drawn to the embodiment of a semiconductor device. The election is made with traverse.

Amendments to the claims begin on page 1 of this paper.

Remarks begin on page 7 of this paper.

CERTIFICATE OF MAILING BY FIRST CLASS MAIL

I hereby certify under 37 CFR \$1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

November 15, 2004
Date of Deposit
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